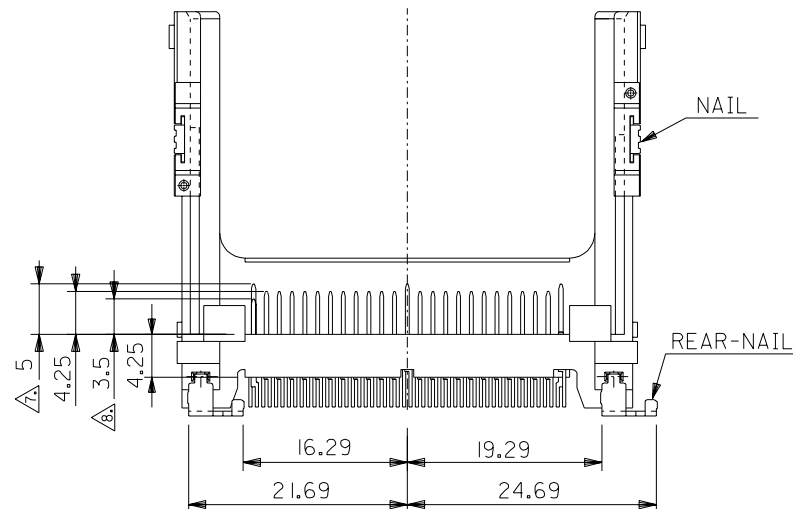
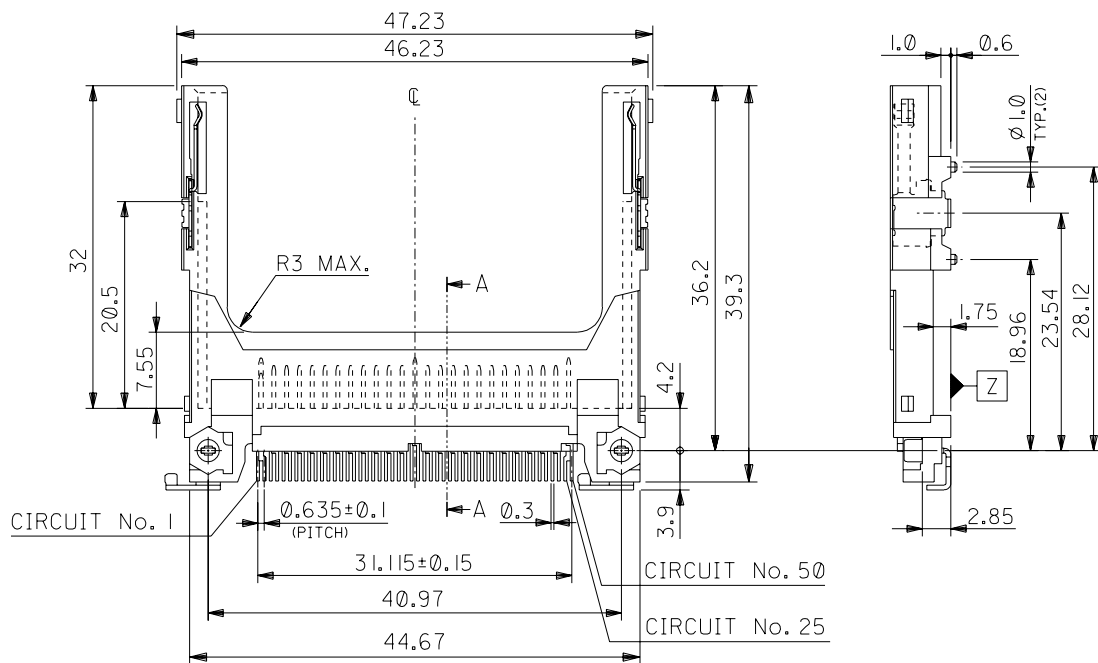
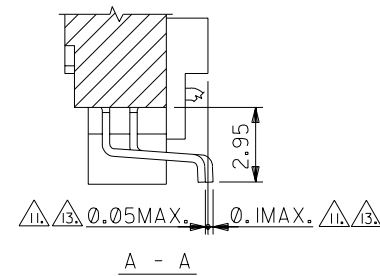


8	7	6	5	4	3	2	EN-02J09
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 THIRD ANGLE PROJECTION		DIMENSIONS: ☐ mm ☐ INCH ☒ mm ONLY		SHT	REV
				REVISE ON CAD ONLY	

MOLEX INCORPORATED

THIS INFORMATION THAT IS PROPRIETARY TO MOLEX SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	SIZE B
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INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.

ET NO.	OF 2	SIZE	B
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EN-02J(097) MXJ-54

DWG. NO. SD-55359-015

F

D

A

C

B

DO NOT SCALE DRAWING

注) 1. 材質
NOTES MATERIAL

ハウジング : ガラス入りLCP UL94V-0
HOUSING: LIQUID CRYSTAL POLYMER G.F. UL94V-0
ピン : リン青銅
PIN: PHOSPHOR BRONZE
ネール : リン青銅 (t0.3)
NAIL: PHOSPHOR BRONZE (t0.3)
リヤネール : リン青銅 (t0.48)
REAR-NAIL: PHOSPHOR BRONZE (t0.48)

2. メッキ仕様
PLATING

ピン
PIN 接点部 : パラジウムニッケル下地、金メッキ
CONTACT AREA: GOLD OVER PALLADIUM-NICKEL PLATING
半田付け部 : 錫メッキ
SOLDER TAIL AREA: TIN PLATING
下地メッキ : ニッケルメッキ
UNDER PLATING: NICKEL ALL OVER PLATING

ネール
NAIL 接点部 : 金メッキ
CONTACT AREA: GOLD PLATING
半田付け部 : 錫メッキ
SOLDER TAIL AREA: TIN PLATING
下地メッキ : ニッケルメッキ
UNDER PLATING: NICKEL ALL OVER PLATING

リヤネール
REAR-NAIL 錫メッキ
TIN PLATING
下地メッキ : ニッケルメッキ
UNDER PLATING: NICKEL ALL OVER PLATING

3. 推奨基板厚 : t=0.8 MIN.
RECOMMENDED P.C.B. THICKNESS: t=0.8 MIN.

4. 適合カード厚
RECOMMENDED CARD THICKNESS
接続部 : 3.3±0.1
CONNECTING AREA: 3.3±0.1

5. 適合カード幅 : 42.8±0.1
RECOMMENDED CARD WIDTH: 42.8±0.1

6. ハウジング色 : 黒
HOUSING COLOR: BLACK

△ 寸法適用極 : 1,13,38,50
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS
1,13,38 AND 50.

△ 寸法適用極 : 25,26
THIS DIMENSION APPLIES TO CIRCUIT NUMBERS 25 AND 26.

△ ピンの倒れは、ピン根元を基準に全方向へ0.1 MAX.とする。
PIN TIP LEAN TOWARD ANY DIRECTION NOT TO EXCEED 0.1
WHEN MEASURED FROM PIN BASE.

△ ピン根元に適用する。
THIS DIMENSION TO BE MEASURED AT PIN BASE.

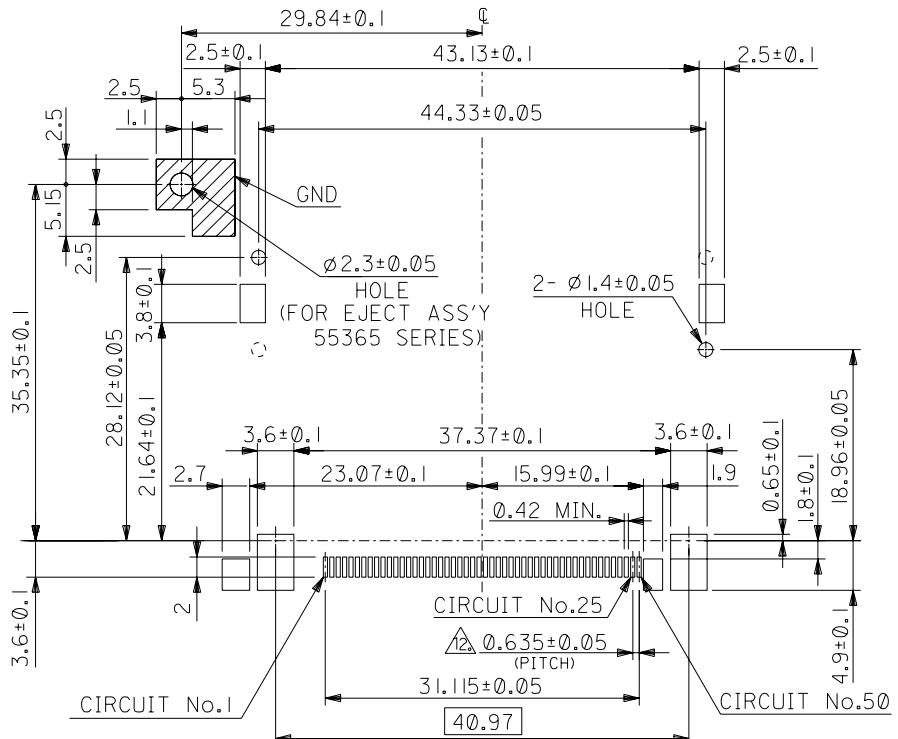
△1. ソルダータールは、Z面を基準とし上へ0.05下へ0.1の範囲にあり、
且つソルダータールの平坦度は、0.1 MAX.とし、テール先端にて測定する。
SOLDERTAILS TO BE WITHIN 0.05 UPWARD AND
0.1 DOWNWARD FROM Z-DATUM PLACE, AND COPLANARITY OF
SOLDERTAILS TO BE WITHIN 0.1.
MEASUREMENT POINT IS SOLDERTAILS TIP.

△2. 公差非累積
NON-CUMULATIVE

△3. テールとネール、リヤネールを併せた平坦度は、0.1 MAX.とする。
TOTAL COPLANARITY OF SOLDER TAILS, NAILS
AND REAR-NAILS TO BE 0.1 MAX.

14. 鉛フリー対応表
CORRESPONDENCE TABLE OF
LEAD FREE

	SEMI-HARD TRAY PKG	SOFT TRAY PKG
半田品 LEAD CONTENT	55359 -5026	55359 -5021
鉛フリー品 LEAD FREE	55359 -5027	55359 -5029



基板推奨寸法
RECOMMENDED P.C.B. LAYOUT

EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		EC NO. DRWN: CH'K: APPR:		RELEASED '04/03/22 EC NO. J2004-3249 DRWN: Y.SAKIYAMA CH'K: M.SASAO APPR: M.SASAO		MATERIAL 材料 注記参照 SEE NOTES		GENERAL TOLERANCES: (UNLESS SPECIFIED) 一般公差		SCALE —		DESIGN UNITS mm □ INCH		THIRD ANGLE PROJECTION		DIMENSIONS: □ mm □ INCH □ mm ONLY		SHT REV	
										注記参照 SEE NOTES		10 UNDER 未満		±0.2		DRAWN BY & DATE Y.Sakiyama '04/03/22		TITLE: CF CARD CONN. 50P HEADER ASS'Y (TYPE I/II, REVERSE) -LEAD FREE-					
												10 OVER 30 UNDER 以上 未満		±0.25		CHECKED BY & DATE H. Sasaki '04/03/22							
												30 OVER 以上		±0.3		APPROVED BY & DATE H. Sasaki '04/03/22							
												WIRE RANGE 適用電線範囲		—		CAD FILENAME SD-55359-015.S02		MATERIAL NO. SEE CHART		DRAWING NO. SD-55359-015		SHEET NO. 2 OF 2	
												INS. RANGE 被覆外径		—		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.				SIZE B			